

## **IXYS Extending ISOPLUS-DIL™ Package Range Less copper, Less Weight, Better Performance**

Biel, Switzerland, May 14, 2009 – IXYS Corporation (NASDAQ: IXYS) announced today the extension of the ISOPLUS-DIL™ package range using the latest generation TrenchMV™ Power MOSFET arranged as 3 identical but electrically separated half-bridges in one package replacing standard 6-pack configurations.

Improvements in the non-planar MOSFET technology, namely trench MOSFETs, resulted in attractive technical advantages to the TrenchMV™ Power MOSFET family. These include lower  $R_{dson}$ , lower gate charge, increased ruggedness and faster switching speed representing a major efficiency improvement.

The appeal of the new “GMM 3x” series is the excellent switching performance by using 3 identical and optimised half-bridges with minimised stray inductance and the disappearance of the internal coupling effects of the traditional 6-pack. The Kelvin source contacts directly connected to the MOSFET die allow best control during the high speed operation of the TrenchMV™ MOSFET family. The construction using Direct Copper Bonded (DCB) ceramic isolation in concert with optimized molding technology creates a best-in-class reliability with extended power cycling capability and excellent thermal performance products.

IXYS provides the “GMM 3x” series in the voltage range of 40 to 150V. GMM 3x160-0055X2-SMD (55V, 150A, 0,0022Ohms with isolated  $R_{thjc} = 1.0$  K/W) and GMM 3x120-0075X2-SMD (75V, 110A, 0,004Ohms) are examples of this new family. The devices can be surface mounted with standard pick and place machines and are suitable for re-flow automated soldering processes for low cost production for our worldwide customers. This unique GMM series offers a lower weight, high power density electrical isolation to a higher degree than discretely or other power modules.

The ISOPLUS-DIL™ GMM series is a very compact and reliable solution for automotive and battery powered applications containing the latest trench MOSFET technology. Combining the low loss switching of the MOSFET with the advanced electrical, thermal and mechanical properties of the ISOPLUS-DIL™ creates an industry-leading solution for both advanced applications such as hydraulic control for automotive systems and standard industrial motor control (e.g. robotics). The advanced packaging system is also customizable for other topologies which are available by request.

Additional product information may be obtained by visiting IXYS website at <http://www.ixys.com>, or by contacting the company directly.

### **About IXYS Corporation**

IXYS Corporation makes and markets technology-driven products to improve power conversion efficiency, generate solar and wind power and provide efficient motor control for industrial applications. IXYS offers a diversified product base that addresses worldwide needs for power control, electrical efficiency, renewable energy, telecommunications, medical devices, electronic displays and RF power.

## **Safe Harbor Statement**

Any statements contained in this press release that are not statements of historical fact, including the performance, rating, availability, reliability and suitability of products for various applications, may be deemed to be forward-looking statements. There are a number of important factors that could cause the results of IXYS to differ materially from those indicated by these forward-looking statements, including, among others, risks detailed from time to time in the Company's SEC reports, including its Form 10-Q for the quarter ended December 31, 2008. The Company undertakes no obligation to publicly release the results of any revisions to these forward-looking statements.

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